



Lead Free Metal Foil Chip Fuse

AEC-Q200 Tested



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IEC 60127-7
EN 60127-1
IEC 60127-1
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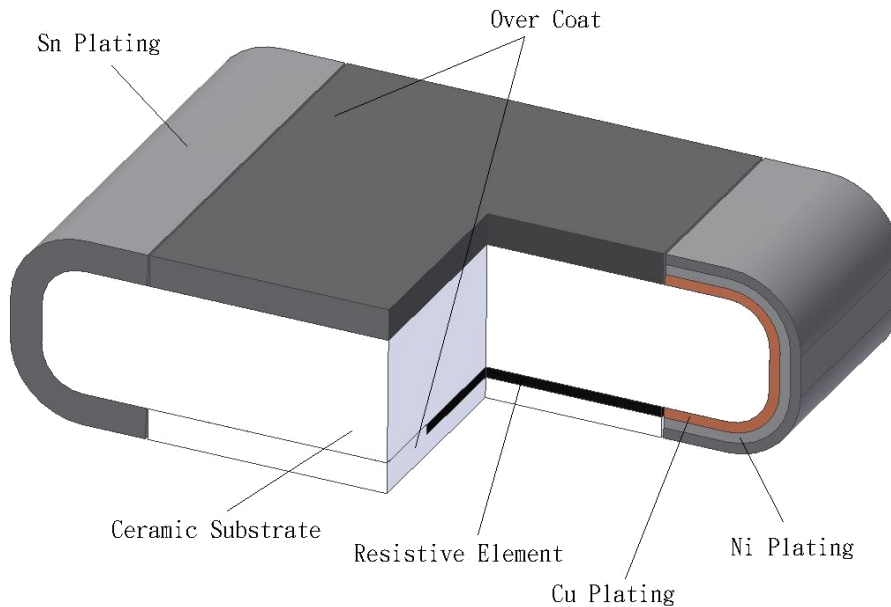


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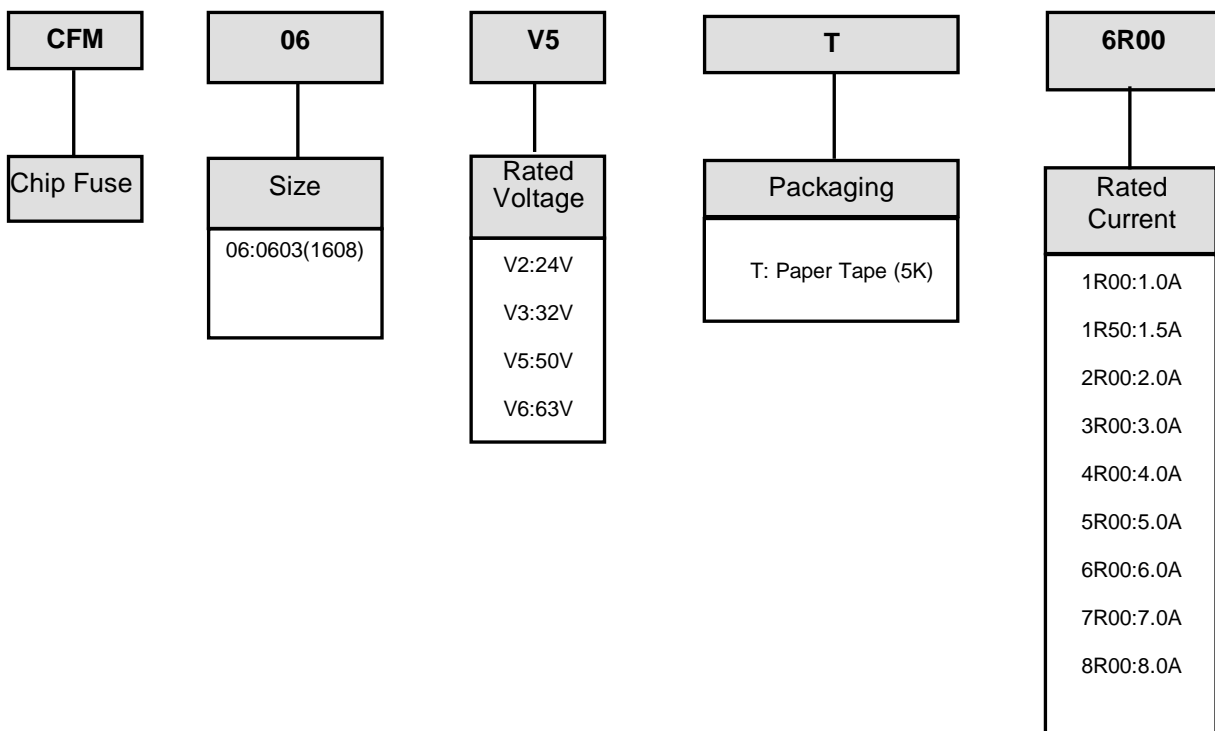
1. Scope

This specification applies for the fuse series of surface mount fuse made by TA-I.

2. Construction



3. Type Designation





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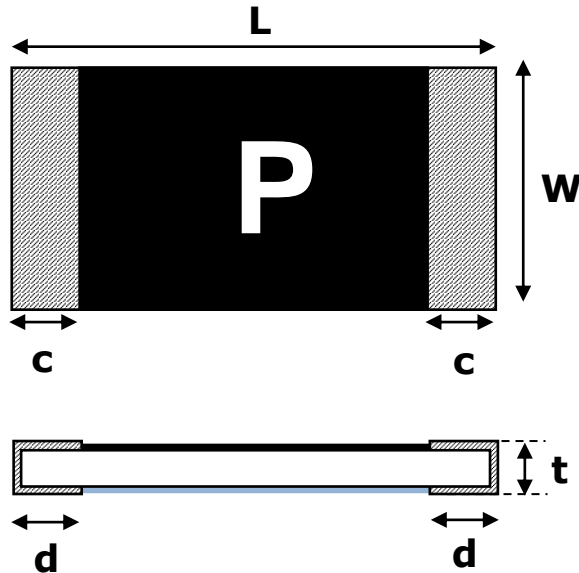


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4. Dimensions



Series	L	W	C	d	t
CFM06	1.6±0.1	0.80±0.1	0.3±0.2	0.3±0.1	0.6±0.10

5. Applications and ratings

Part Designation	Marking	Rated Current	Resistance (mΩ) Tolerance ±25%	Typical I ² t (A ² s)	Fusing Time	Rated Voltage	Breaking Capacity	Body Temperature rising
CFM06V5T1R00	L	1.00A	115.00	0.059	Open within 1~120sec. at 200% rated current	DC 50V DC 63V	DC 50V 50A	< 75°C at 100% rate current
CFM06V5T1R50	P	1.50A	59.00	0.130				
CFM06V5T2R00	S	2.00A	33.00	0.210				
CFM06V5T3R00	3	3.00A	15.90	0.710				
CFM06V5T4R00	W	4.00A	10.00	0.960				
CFM06V5T5R00	Y	5.00A	6.77	2.050				
CFM06V5T6R00	6	6.00A	6.30	3.470				
CFM06V5T7R00	7	7.00A	4.70	5.040				
CFM06V5T8R00	8	8.00A	4.30	6.500				

Note:

1. Typical I²t value is measured at 10x-rated current, Application with surge over 10x-rated current. Please confirm with us.
2. Rate voltage 63V UL only.



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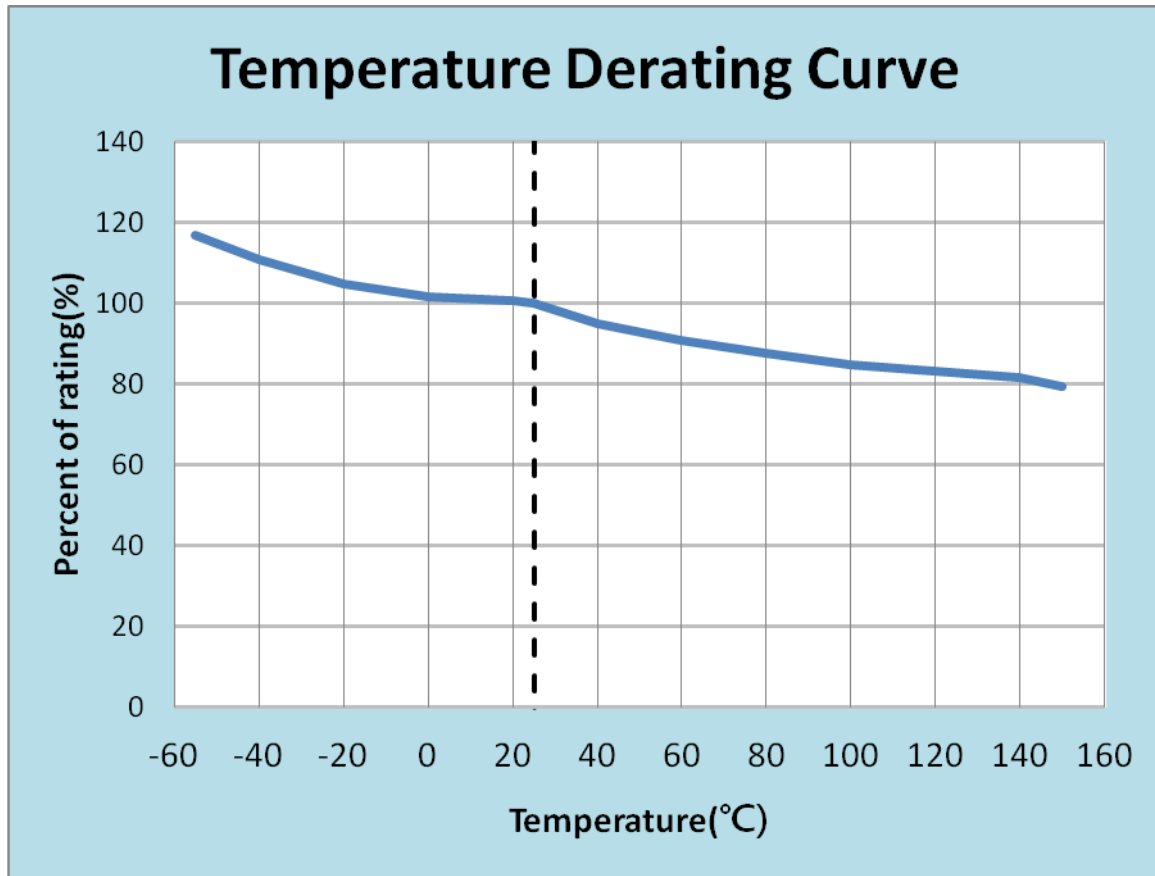


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6. Temperature Derating Curve

6.1 Normal Ambient Temperature: 25°C

6.2 Operating Temperature: -55°C~150°C, with proper Derating factor as below:



7. Reliability Tests

No.	Parameter	Test Method	Requirement
#1	Solderability	aging 4 hours at 150 °C dry heat Lead-free solder bath at 245±3 °C for 3±0.5 seconds. 260±3 °C for 7±0.5 seconds	95% coverage minimum
#2	Resistance to solder Heat	Immerse the specimens in and eutectic solder at 260+5/-0°C for 10±1S.	±10%
#3	Moisture Resistance	T=24 hours / Cycle ,10Cycles. Notes: Steps 7a& 7b not required. Unpowered.	±10%
#4	Thermal Shock	Temperature -55°C/+155°C. Number of cycles required:300 Maximum transfer time-20 seconds, Dwell time-15 minutes. Air-Air.	±10%
#5	Mechanical Shock	Wave Form: Tolerance for half sine shock pulse. Peak value is 100g's. Normal duration(D) is 6(ms)	±10%



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#6	Vibration	5 g's for 20 min., 12 cycles each of 3 orientations. (Note: Test from 10-2000 Hz.)	±10%
#7	Terminal Strength	Force of 1.8kg for 0603	±10%
#8	High Temperature Storage	with exemptions 1000 hrs. @ T=125°C. Unpowered. Measurement at 24±2 hours after test conclusion.	±10%
#9	Temperature Cycling	1000 Cycles (-40°C to +125°C) 30min maximum dwell time at each temperature extreme. 1 min. Maximum transition time. Measurement at 24±4 hours after test conclusion.	±10%
#10	Bias Humidity	1000 hours 85°C/85%RH. Note: Specified conditions: 10% of operating current. Measurement at 24±2 hours after test conclusion.	±10%
#11	Operational Life	1000 hours TA=85°C at 70% rated current. Measurement at 24±2 hours after test conclusion	±10%
#12	Resistance to Solvent	a:Isopropyl Alcohol : Mineral Spirits= 1 : 3 b:Terpene Defluxer (Bioact EC-7R) c:Deionized water : Propylene Glycol : Monomethyl Ether : monoethanolamine = 42 : 1 : 1	No evident damages on protective coating
#13	Board Flex (Bending)	3mm deflection	±10%
#14	Carrying capacity	Rated current ,4hr	±10%
#15	Fusing Time	200% of its rated current	1~120 sec
#16	Interrupting Ability	After the fuse is interrupted, rated voltage applied for 30sec again	No mechanical damages
#17	Temperature Rise	100% of its rated current, Measure of surface temperature	Δ T<75°C
#18	Residual Resistance	Measure DC resistance after fusing	10kΩ and more
#19	Low Temperature Storage	1000 hrs. @ T=-55°C. Unpowered. Measurement at 24±2 hours after test conclusion.	±10%

8. Marking

Symbol for Rating Current

Symbol	L	P	S	3	W	Y	6	7	8
Rating Current(A)	1.0	1.5	2.0	3.0	4.0	5.0	6.0	7.0	8.0



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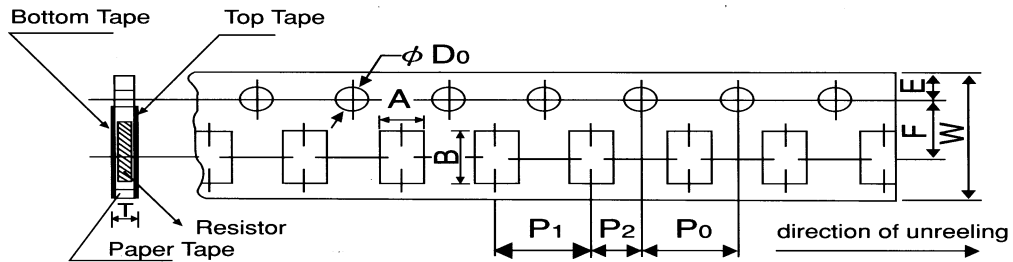


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9. Taping & Reel

9.1 Taping Dimensions

4mm pitch paper

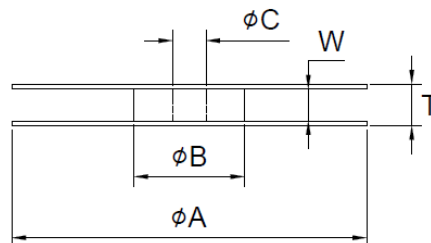
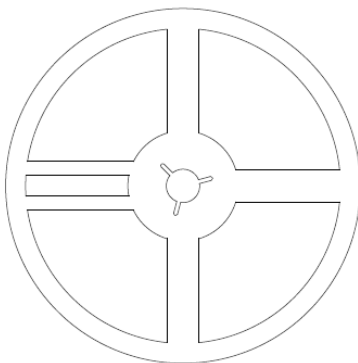


Packing	Type	A	B	W	F	E	P ₁	P ₂	P ₀	D ₀	T
Paper Tape	CFM06	1.1±0.1	1.9±0.1	8.0±0.2	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	φ 1.5 ^{+0.1} ₋₀	0.64±0.1

Unit: mm

Type series		Paper Tape
		4 mm pitch
		180mm/R
CFM	06	5000

9.2 Reel Specifications



Unit: mm

Series	φ A	φ B	φ C	W	T
CFM06	178±2.0	60.0±1.0	13.0±1.0	9.0±1.0	11.4±2.0

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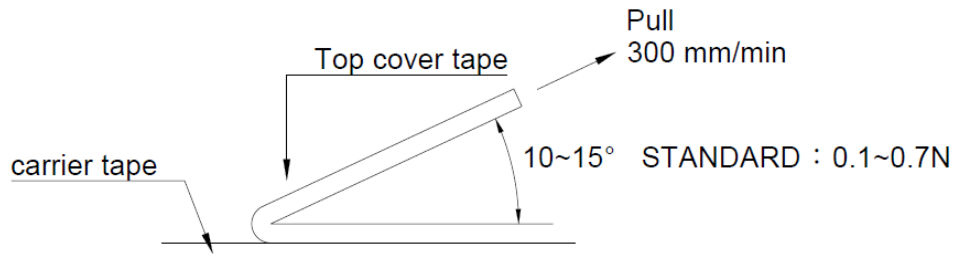


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9.3 Peel –off force:



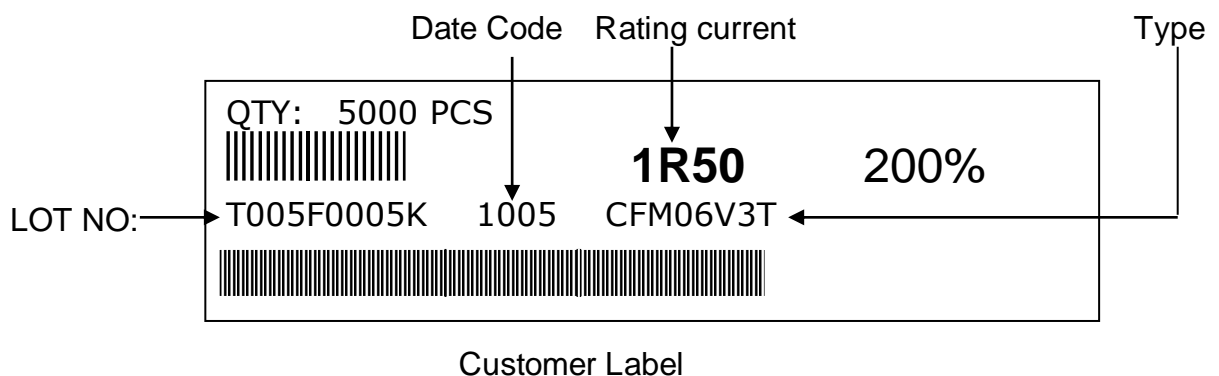
10. Storage Conditions:

Temperature: 5°C ~35°C ,Humidity:40%~75%.

11. Shelf Life:

2 years from manufacturing date.

12. Label





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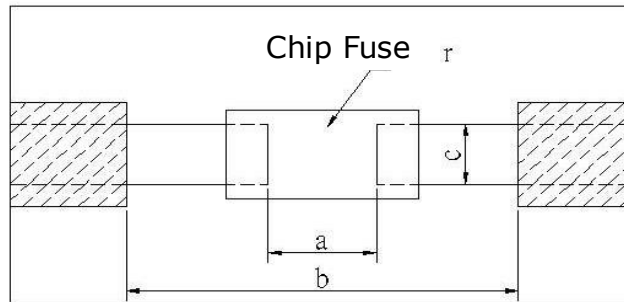


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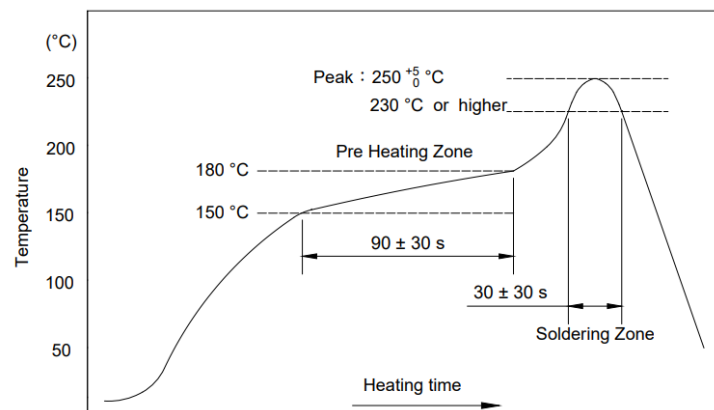
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13. Recommended land patterns



Type	Land pattern Size	Dimension		
		a	b	c
CFM	06 (0603)	0.7~0.9	2.0~2.2	0.8~1.0

14. Recommend IR – Reflow profile: (solder: Sn96.5 / Ag3 / Cu0.5)



Peak : $250 \begin{matrix} +5 \\ -0 \end{matrix}^{\circ}\text{C}$, 5 sec

Pre – heat Zone : 150 to 180 °C , 90±30 sec.

Soldering Zone : 230°C or higher , 30±10 sec.

15. Approval by UL248-14

The fuses have been approved by UL.

File No. of UL Recognition is E241710



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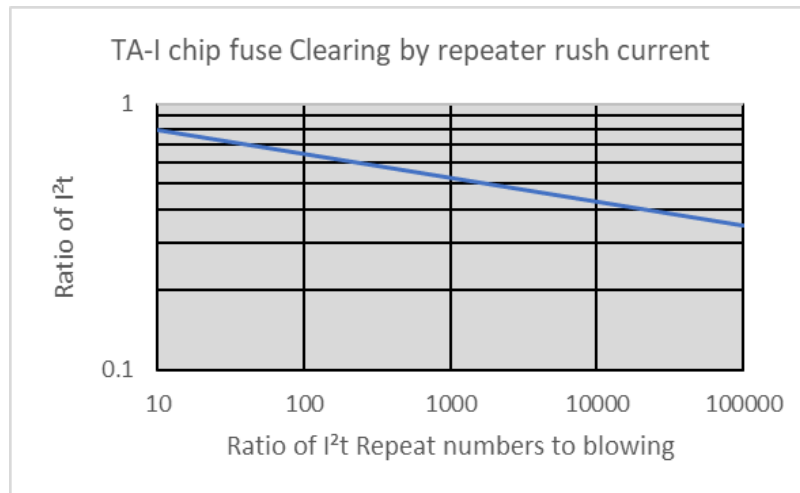


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16. Pulses derating curve:



17. ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.

18. Manufacturing Country & City:

TA-I TECHNOLOGY CO., LTD. (Taiwan– Tao Yuan)

Tel: (+886) 3-3246169

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Associated companies:

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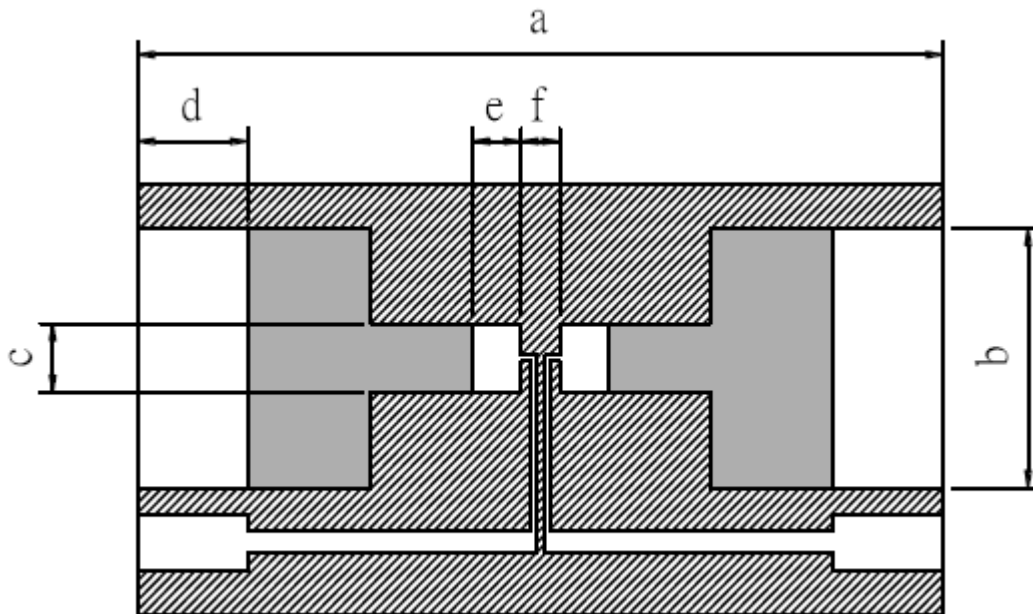


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19. Test Circuit Board :



Type	a	b	c	d	e	f
CFM0603	19	6	1.6	2.6	1.15	0.9



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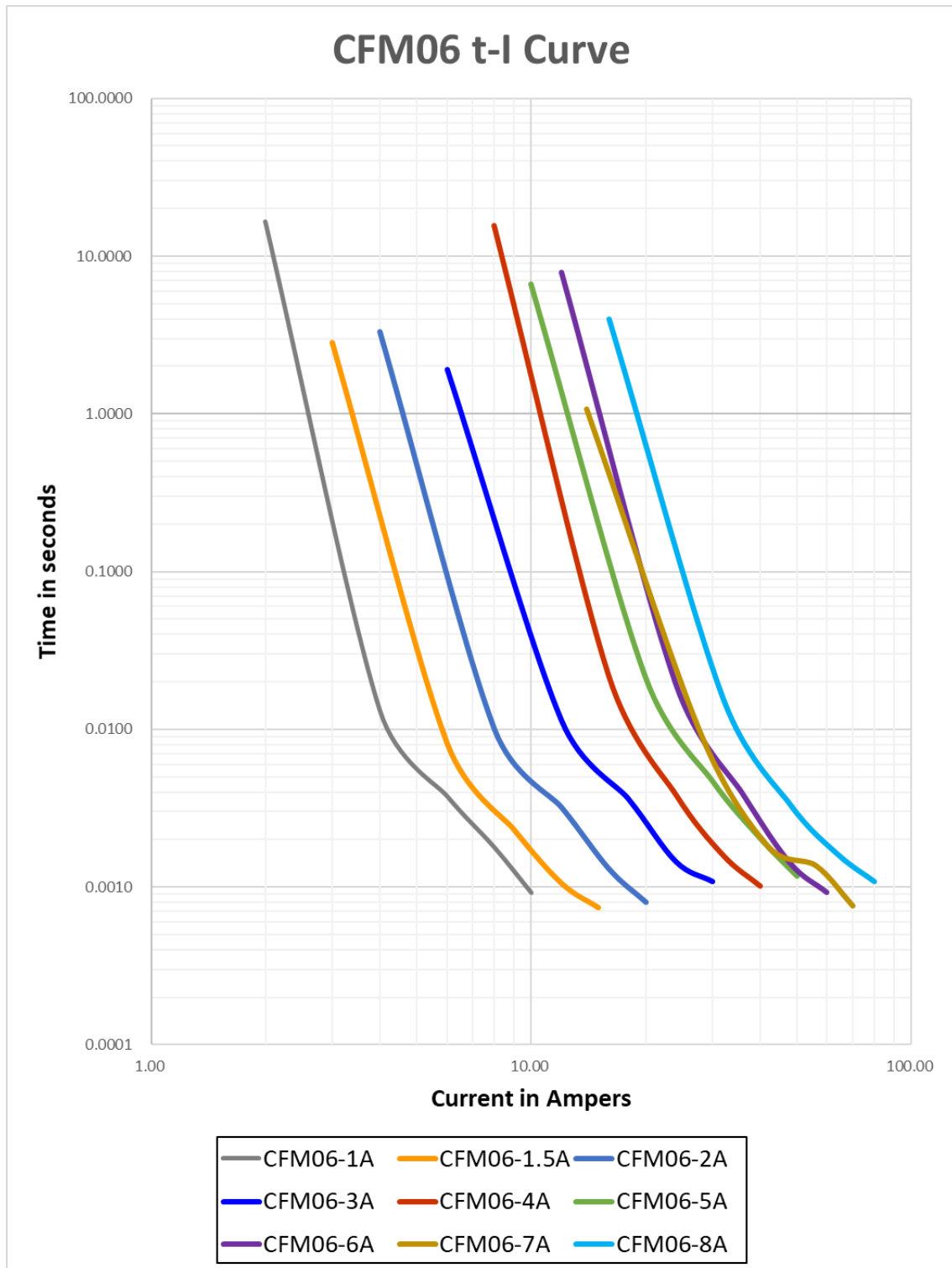


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20.TA-I 0603 Metal Foil Chip Fuse I-t Curve:





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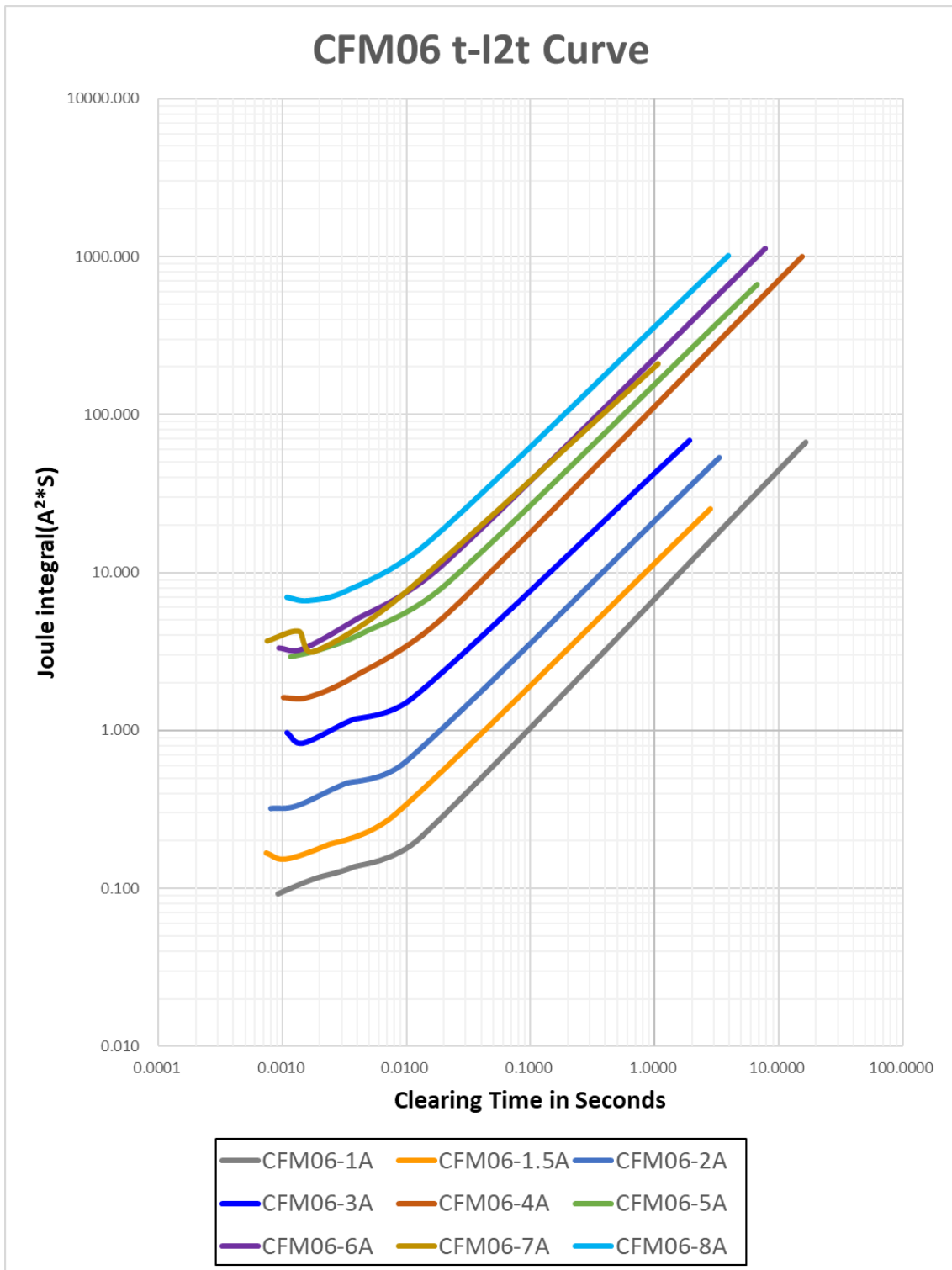


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22.TA-I 0603 Metal Foil Chip Fuse I2-t Curve



单击下面可查看定价，库存，交付和生命周期等信息

[>>TA-I\(大毅\)](#)